

Method for coating surfaces on copper or on a copper alloy with a tin or tin alloy layer

Abstract:

With known methods of tin-plating copper surfaces, no sufficiently good soldering results are obtained. In particular, the surfaces do not remain suitable for soldering after thermal treatment. To solve this problem, a method for coating surfaces on copper or on a copper alloy with a layer of tin or a tin alloy is used which has the following essential method steps: a. Treatment of the surfaces with a solution containing at least one noble metal compound, in order to deposit noble metal; b. Treatment of the surfaces coated with noble metal as per step a. with a solution containing at least one tin compound, at least one acid and at least one complexing agent for copper from the group consisting of thiourea and its derivatives, in order to form the tin or tin alloy layer.
